

Dual P-Channel MOSFET

DESCRIPTION

SMC4953A is the Dual P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance. This device is ideal for load switch applications.

PART NUMBER INFORMATION

SMC **4953A** **M** - **TR** **G**
 a b c d e

- a : Company name.
- b : Product Serial number.
- c : Package code M: SOP-8
- d : Handling code TR: Tape & Reel
- e : Green produce code G: *RoHS Compliant*

FEATURES

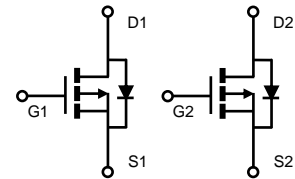
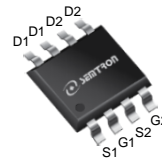
$V_{DS} = -30V$, $I_D = -5A$

$R_{DS(ON)} = 46m\Omega (Typ.) @ V_{GS} = -10V$
 $R_{DS(ON)} = 65m\Omega (Typ.) @ V_{GS} = -4.5V$

- ◆ Fast switch
- ◆ High power and current handling capability

APPLICATIONS

- ◆ DC-DC Power System
- ◆ Load Switch



SOP-8

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ C$	-5
		$T_A = 70^\circ C$	-4
I_{DM}	Pulsed Drain Current ^A	-20	A
P_D	Power Dissipation ^B	$T_A = 25^\circ C$	2
		$T_A = 70^\circ C$	1.3
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^C	Steady-State	62	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^C		110	
$R_{\theta JC}$	Thermal Resistance Junction to Case ^C		45	

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise noted)

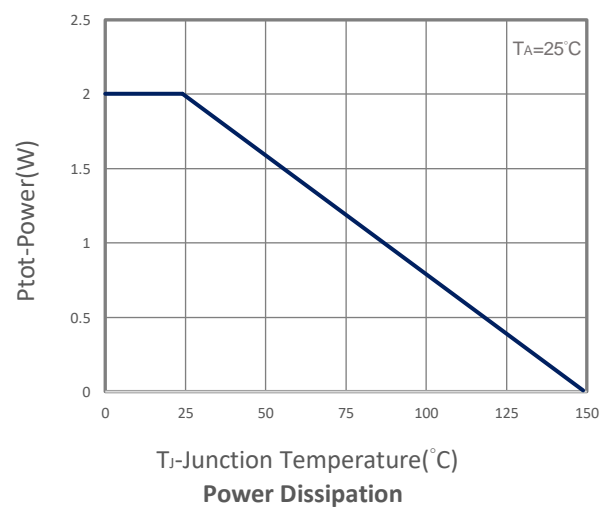
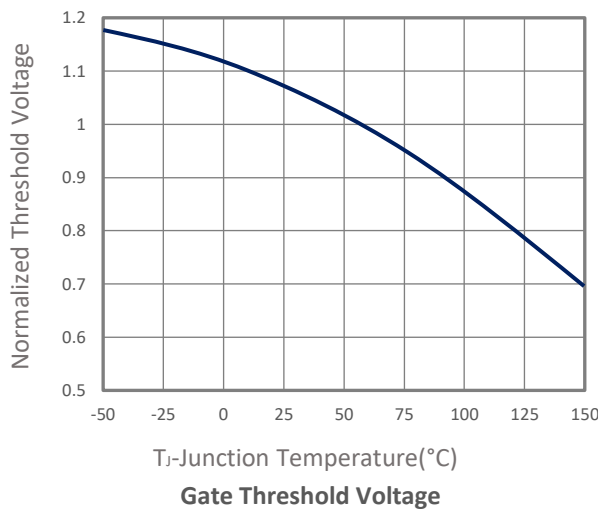
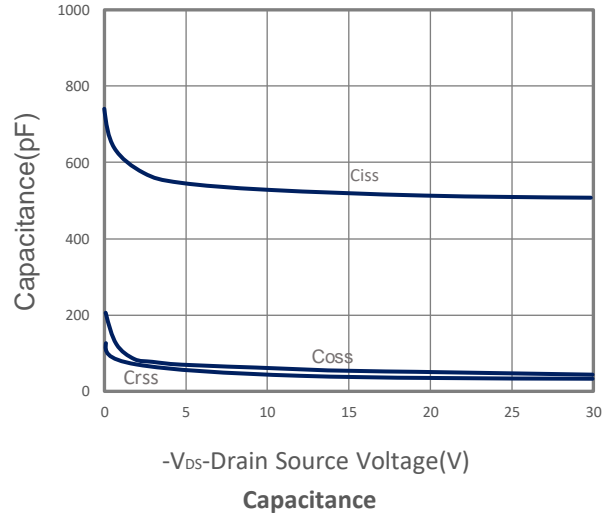
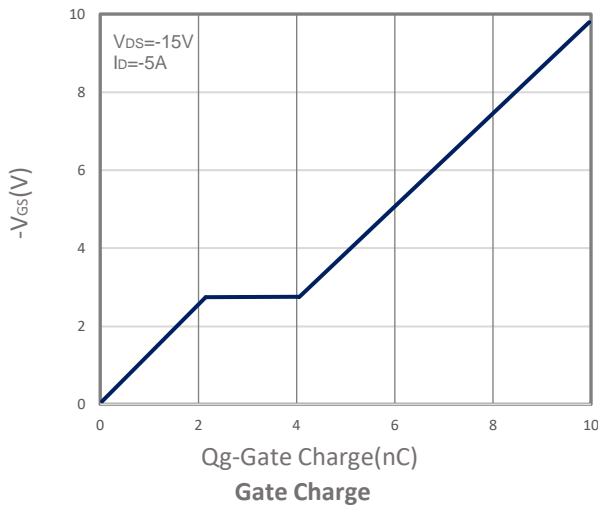
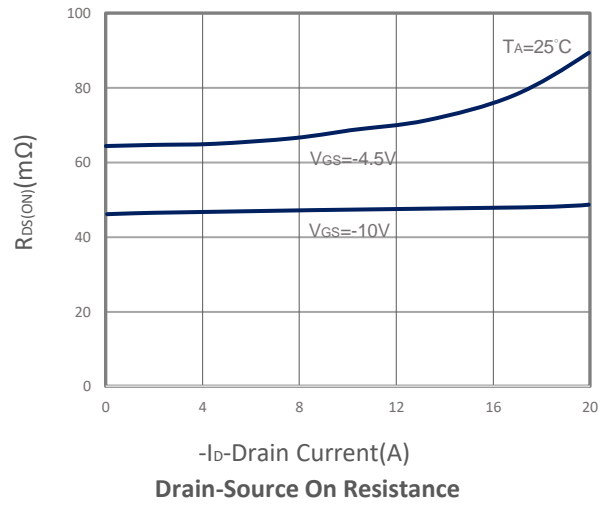
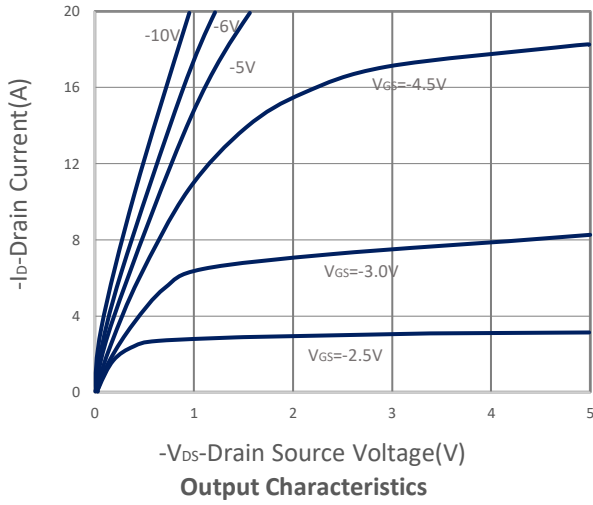
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-30			V	
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1	-1.6	-2.5	V	
I _{GSS}	Gate Leakage Current	V _{DS} = 0V, V _{GS} = ±20V			±100	nA	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -30V, V _{GS} = 0V T _J = 25°C			-1	μA	
		V _{DS} = -24V, V _{GS} = 0V T _J = 75°C			-10		
R _{DS(ON)}	Drain-source On-Resistance ^D	V _{GS} = -10V, I _D = -5A V _{GS} = -4.5V, I _D = -3.6A		46 65	52 75	mΩ	
G _{fs}	Forward Transconductance	V _{DS} = -10V, I _D = -5A		8.7		S	
Diode Characteristics							
V _{SD}	Diode Forward Voltage ^B	I _S = -1A, V _{GS} = 0V		-0.7	-1	V	
I _S	Continuous Source Current				-2.5	A	
Dynamic and Switching Parameters							
Q _g	Total Gate Charge (10V)	V _{DS} = -15V, V _{GS} = -10V I _D = -5A		10.8	15.1	nC	
Q _g	Total Gate Charge (4.5V)			5.4	7.6		
Q _{gs}	Gate-Source Charge			2.1	2.9		
Q _{gd}	Gate-Drain Charge			1.8	1.4		
C _{iss}	Input Capacitance	V _{DS} = -15V, V _{GS} = 0V f = 1MHz		512	717	pF	
C _{oss}	Output Capacitance			52	73		
C _{rss}	Reverse Transfer Capacitance			43	60		
t _{d(on)}	Turn-On Time ^E	V _{DD} = -15V, V _{GEN} = -10V, R _G = 3.3Ω, I _D = -1A		7.5		nS	
t _r				10			
t _{d(off)}			Turn-Off Time ^E		22		
t _f					6		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

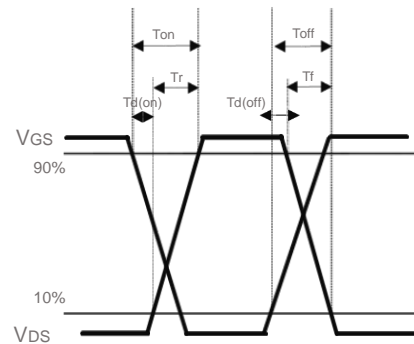
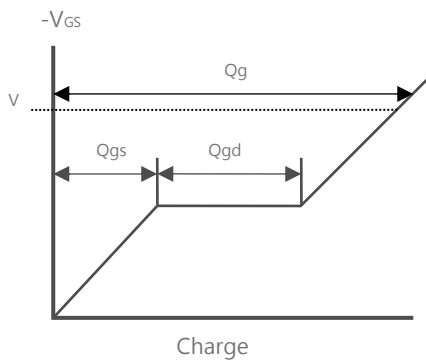
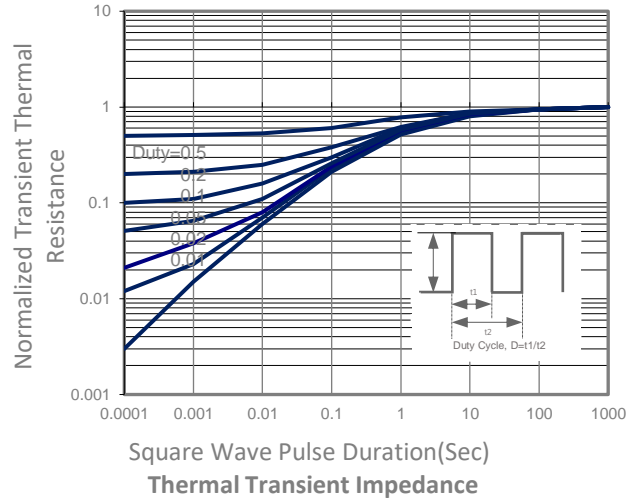
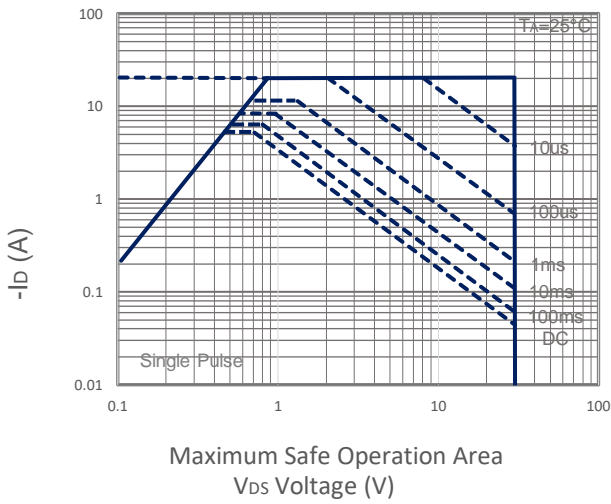
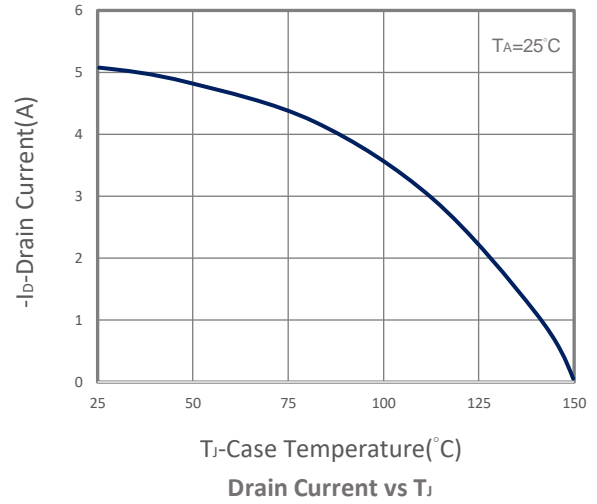
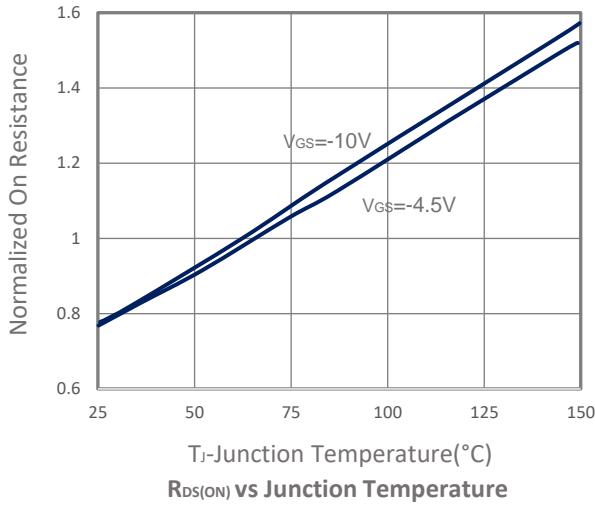
- A. Pulse width limited by maximum junction temperature T_{J(MAX)} = 150°C (initial temperature T_J = 25°C).
- B. The T_{J(MAX)} = 150°C, using junction-to-ambient thermal resistance.
- C. Surface-mounted on FR-4 board using 1 sq-in pad, 2 oz Cu, in a still air environment with T_A = 25°C.
- D. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
- E. Pulsed width limited by maximum junction temperature.
- F. The EAS data shows Max.

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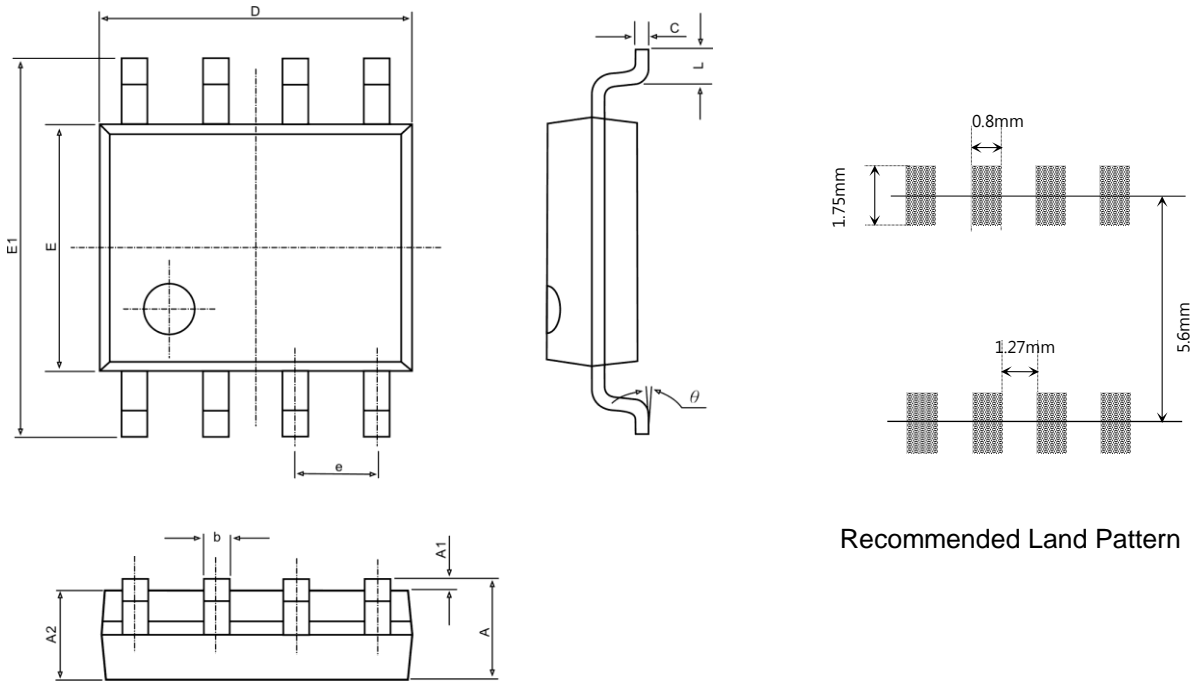
TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



■ SOP-8 PACKAGE DIMENSIONS



Recommended Land Pattern

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.040	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.130	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270BSC.		0.050BSC.	
L	0.400	1.270	0.016	0.005
θ	0°	8°	0°	8°